

整理番号=990293

提出日 平成11年10月13日
特願平11-291576 頁: 1/ 4

~~【書類名】 図面~~

~~【図1】~~

FIG. 1 A

~~(A)~~

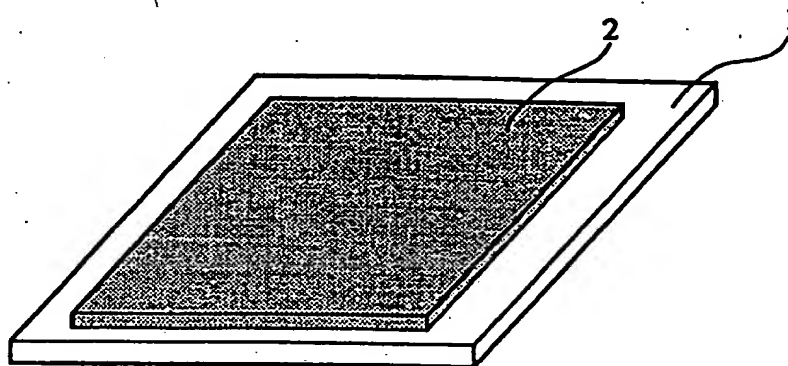
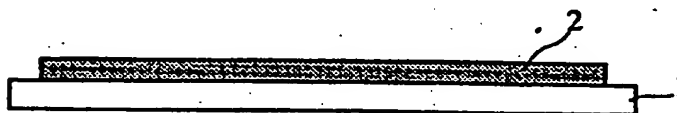


FIG. 1 B

~~(B)~~

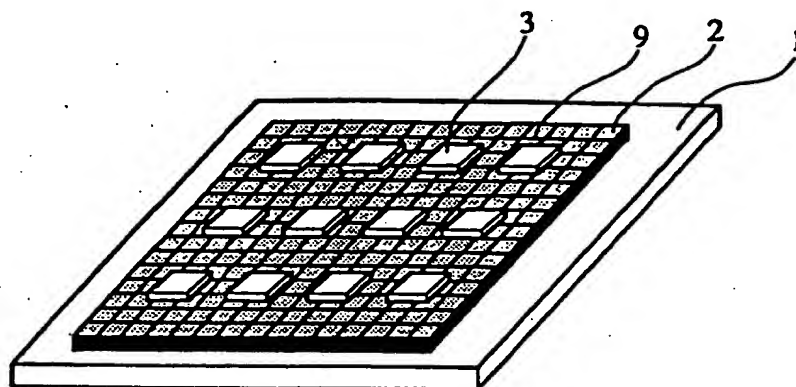


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~~【図4】~~

FIG. 4

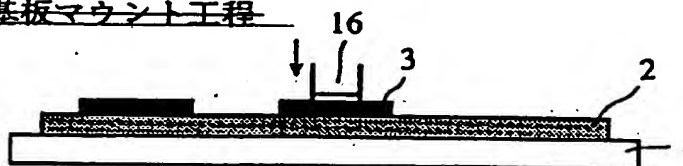


~~【図5】~~

SUBSTRATE MOUNTING PROCESS

FIG. 5A

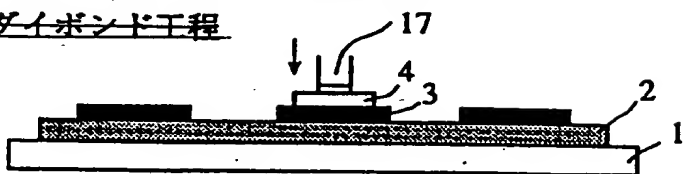
~~(a) 基板マウント工程~~



DIE BONDING PROCESS

FIG. 5B

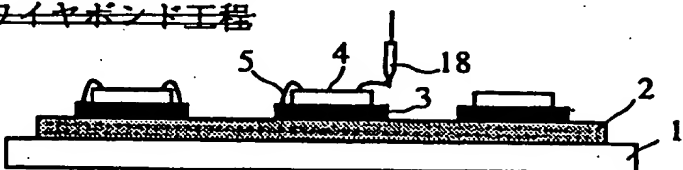
~~(b) ダイボンディング工程~~

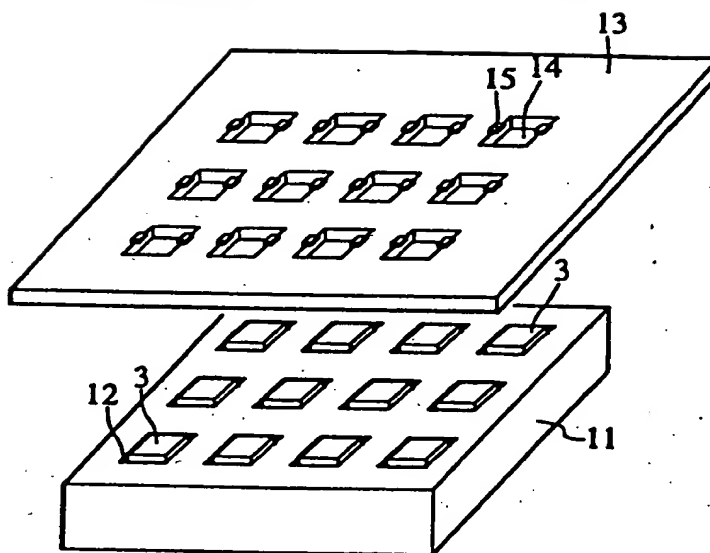


WIRE BONDING PROCESS

FIG. 5C

~~(c) ワイヤボンディング工程~~

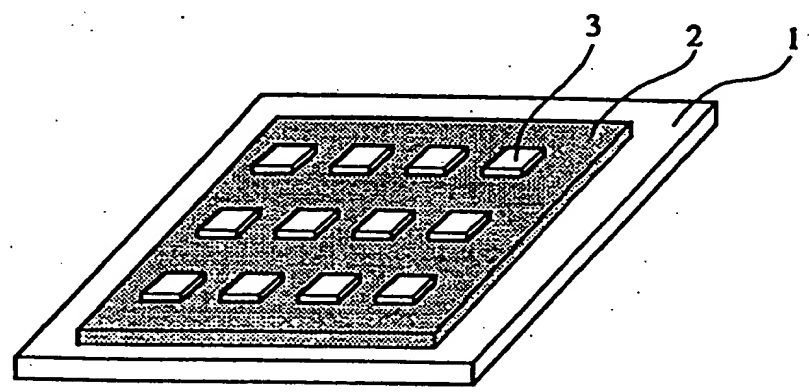




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FIG. 8



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FIG. 9 A

SUBSTRATE MOUNTING PROCESS
~~(a) 基板マウント工程~~

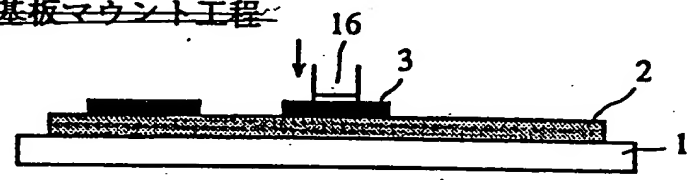


FIG. 9 B

DIE BONDING PROCESS
~~(b) ダイボンド工程~~

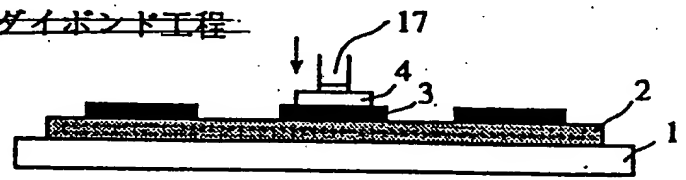
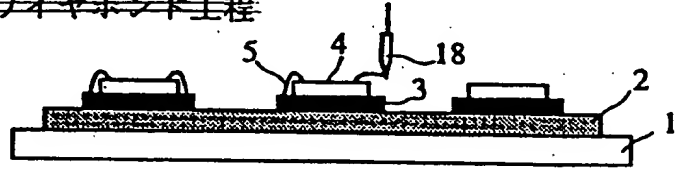


FIG. 9 C

WIRE BONDING PROCESS
~~(c) ワイヤボンド工程~~

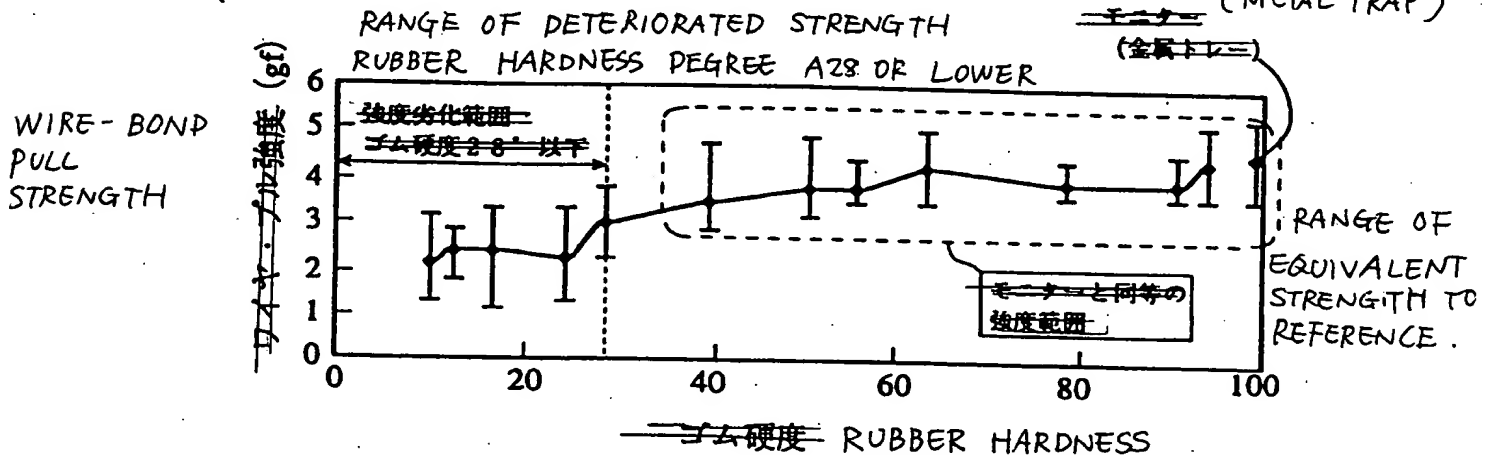


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【図8】

(10)

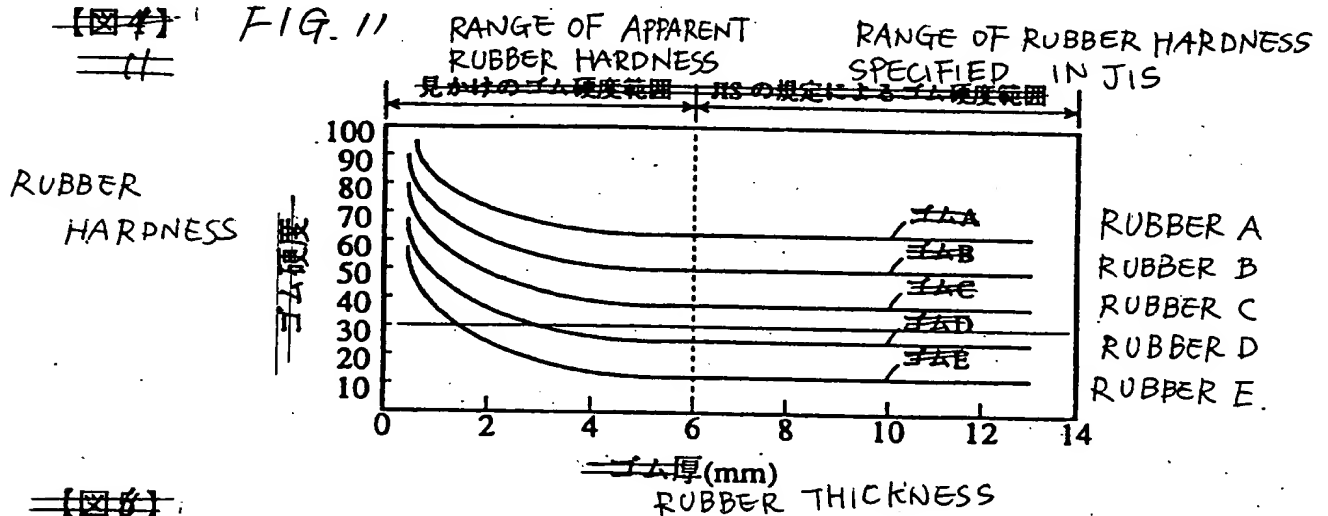
FIG. 10



【図9】

(11)

FIG. 11

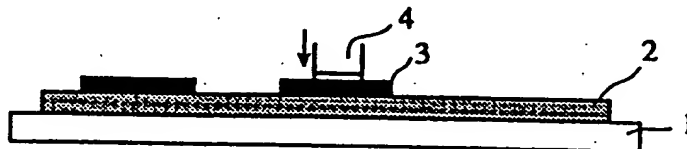


【図10】

(12)

(a) 基板マウント工程 SUBSTRATE MOUNTING PROCESS

FIG. 12 A



BUMP BONDING PROCESS

(b) バンプ接合工程

FIG. 12 B

